Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: <u>ti.com/support</u>

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: **06/11/2022**

Details for "TPS62147RGXT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS62147RGXT	NIPDAU	Level-1-260C-UNLIM	TI PHILIPPINES CLARK A/T	RGX 11	3x2x0.9	13.4

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
Component				Percentage %	ppm	Percentage %	ppm
Lead Frame		•			·		
Copper and Its Alloys	Copper	7440-50-8	4.723114	97.585	975850	35.329659	353297
Copper and Its Alloys	Iron	7439-89-6	0.11132	2.3	23000	0.832692	8327
Copper and Its Alloys	Phosphorus	7723-14-0	0.000726	0.015	150	0.005431	54
Zinc and Its Alloys	Zinc	7440-66-6	0.00484	0.1	1000	0.036204	362
Sub-Total			4.84	100	1000000	36.203985	362040
Lead Frame Plating	•	•		-		-	
Nickel and Its Alloys	Nickel	7440-02-0	0.041853	95.120455	951205	0.313067	3131
Precious Metals	Gold	7440-57-5	0.000343	0.779545	7795	0.002566	26
Precious Metals	Palladium	7440-05-3	0.001804	4.1	41000	0.013494	135
Sub-Total			0.044	100	1000000	0.329127	3291
Mold Compound		-			-		
Other Inorganic Materials	Fused Silica	60676-86-0	4.64965	73.500017	735000	34.780136	347801
Other Inorganic Materials	Silica	7631-86-9	0.948908	15.000001	150000	7.097986	70980
Other Plastics and Rubber	Carbon Black	1333-86-4	0.03163	0.499996	5000	0.236598	2366
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.03163	0.499996	5000	0.236598	2366
Other Plastics and Rubber	Silicone	218163-11-2	0.03163	0.499996	5000	0.236598	2366
Thermoplastics	Ероху	85954-11-6	0.632605	9.999995	100000	4.731988	47320
Sub-Total			6.326053	100	1000000	47.319903	473199
Semiconductor Device	•	-	-	-		-	
Ceramics / Glass	Doped Silicon	7440-21-3	2.034178	100	1000000	15.215981	152160
Sub-Total			2.034178	100	1000000	15.215981	152160
Solder Bump							
Copper and Its Alloys	Copper	7440-50-8	0.109677	88.120164	881202	0.820402	8204
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.014039	11.279657	112797	0.105014	1050
Precious Metals	Silver	7440-22-4	0.000747	0.600178	6002	0.005588	56
Sub-Total			0.124463	100	1000000	0.931003	9310
							
Total			13.368694			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/11/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.